



SDI Review Form 1.6

Journal Name:	Journal of Materials Science Research and Reviews
Manuscript Number:	Ms_JMSRR_42082
Title of the Manuscript:	The Study of Creep Properties of Sn-5wt%Sb Lead-Free Solders with Annealing Temperature
Type of the Article	Original Research Article

General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/page.php?id=sdi-general-editorial-policy#Peer-Review-Guideline>)

PART 1: Review Comments

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Compulsory REVISION comments	1) Annealing in which environment? 2) Sn-Sb phase diagram 3) Why the creep resistance increases with increasing temperature? 4) Why creep resistance is evident at low temperature? 5) For equation 4 must be given reference; advances and disadvantages.	
Minor REVISION comments		
Optional/General comments		

Reviewer Details:

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